

## 676-Ball Fine-Pitch BGA (FG676/FGG676) Package

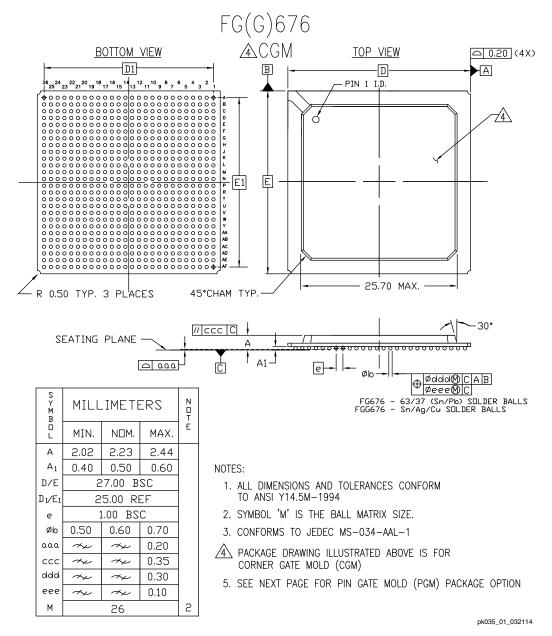


Figure 1: Corner Gate Mold Option, FG676/FGG676 Package

© Copyright 2005–2014 Xilinx, Inc. Xilinx, the Xilinx logo, Artix, ISE, Kintex, Spartan, Virtex, Vivado, Zynq, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners.



2

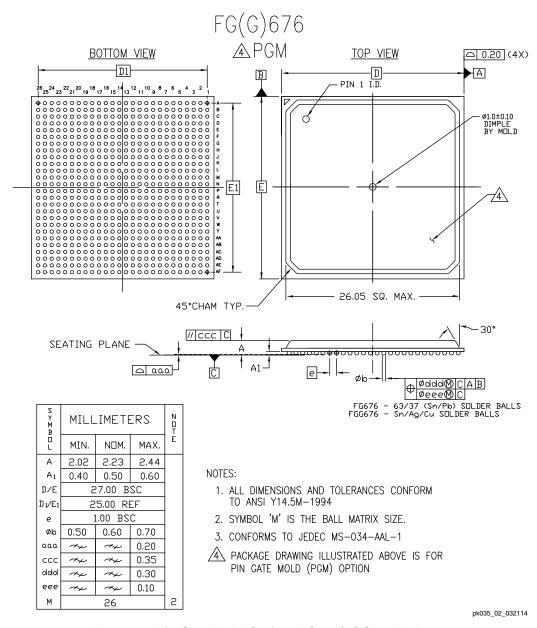


Figure 2: Pin Gate Mold Option, FG676/FGG676 Package

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/15/2011	1.3	Revised tolerances for symbol A.
04/04/2014	1.4	Added Figure 2, pin gate mold package as described in XCN12023.

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.